RICOH

R1200x SERIES

STEP-UP DC/DC CONVERTER FOR OLED BACK LIGHT with SHUTDOWN FUNCTION

NO.EA-192-170925

OUTLINE

R1200x series are CMOS-based control type step-up DC/DC converter with low supply current ICs. Each of these ICs consists of a Nch MOSFET, NPN transistor, an oscillator, PWM comparator, a voltage reference unit, an error amplifier, a current limit circuit, an under voltage lockout circuit (UVLO), an over voltage protection circuit (OVP), and a soft start circuit. As the external components, an inductor, resistances or capacitors are necessary to make a constant output voltage of step-up DC/DC converter with the R1200x. At standby mode, the NPN transistor can separate the output from the input. During the situation of that, there are two versions. R1200xxxxA: the output of Vout is generated to 0V by the low resistance (with the auto discharge function). R1200xxxxB does not generate the output of Vout (without the auto discharge function).

The soft-start time (Typ. 1.5ms) and the maximum duty cycle (Typ. 91%) are set internally. For the protection functions of R1200x series are the current limit function of the Lx peak current, the OVP function for detection the over voltage of output and the UVLO function for protective miss-operation by the low voltage. (The threshold of OVP is selectable from 17V, 19V or 21V.)

Since the packages for these ICs are DFN1616-6, DFN(PLP)1820-6, SOT-23-6 and WLCSP-6-P1, therefore high density mounting of the ICs on boards is possible.

FEATURES

- Supply CurrentTyp. 500μA
- Standby Current......Max. 3µA
- Input Voltage Range2.3V to 5.5V
- Feedback Voltage1.0V (Externally adjustable)
- Feedback Voltage Accuracy......±1.5%
- Temperature-Drift Coefficient of Feedback Voltage±150ppm/°C
- Oscillator FrequencyTyp. 1.2MHz
- Maximum Duty CycleTyp. 91%
- Switch ON ResistanceTyp. 1.35Ω
- UVLO Detector Threshold......Typ. 2.0V
- Soft-start Time......Typ. 1.5ms
 Lx Current Limit ProtectionTyp. 700mA

- Switching ControlPWM
- Built-in a rectifier NPN transistor, at standby mode, complete shutdown is possible.
- Built-in Auto discharge function.....A version
- PackagesDFN1616-6, DFN(PLP)1820-6, SOT-23-6,
 - WLCSP-6-P1
- Ceramic capacitors are recommended......1 μF

APPLICATION

- OLED power supply for portable equipment
- White LED Backlight for portable equipment

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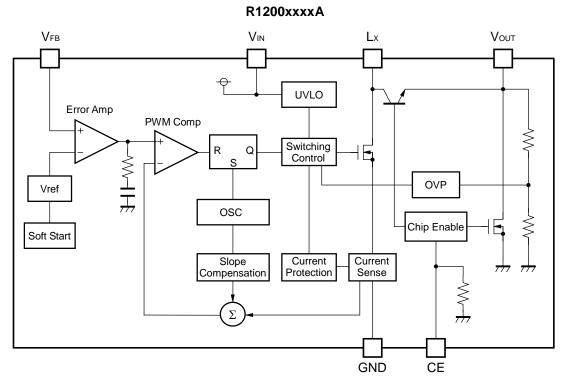
SELECTION GUIDE

The OVP threshold voltage, auto discharge function, and the package for the ICs can be selected at the user's request.

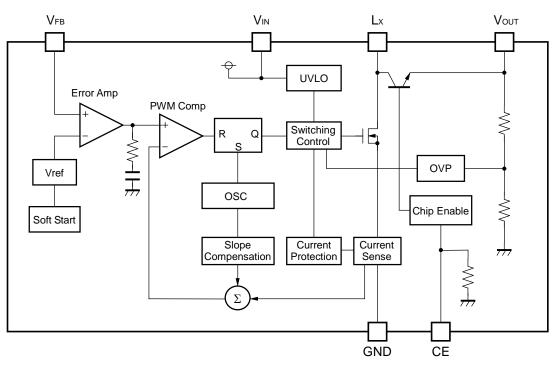
Product Name	Package	Quantity per Reel	Pb Free	Halogen Free		
R1200Zxxx*-E2-F	WLCSP-6-P1	5,000 pcs	Yes	Yes		
R1200Lxxx*-TR	DFN1616-6	5,000 pcs	Yes	Yes		
R1200Kxxx*-TR	DFN(PLP)1820-6	5,000 pcs	Yes	Yes		
R1200Nxxx*-TR-FE	SOT-23-6 3,000 pcs Yes Yes					
xxx : Designation of OVP detector threshold (001) 17V threshold of OVP (002) 19V threshold of OVP (003) 21V threshold of OVP						
 * : The auto discharge function at off state are options as follows. (A) with auto discharge function at off state (B) without auto discharge function at off state 						

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BLOCK DIAGRAMS



R1200xxxxB



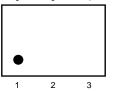
DFN1616-6

R1200x

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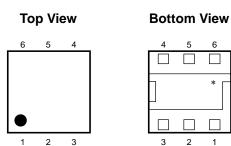
PIN DESCRIPTIONS

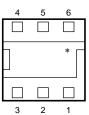
WLCSP-6-P1 **Top View** 5



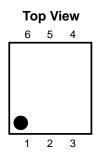
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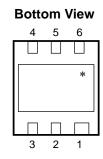
Bottom View



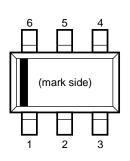


DFN(PLP)1820-6





SOT-23-6



WLCSP-6-P1

Pin No	Symbol	Pin Description	
1	Lx	Switching Pin (Open Drain Output)	
2	Vin	Power Supply Input Pin	
3	VFB	Feedback Pin	
4	CE	Chip Enable Pin ("H" Active)	
5	Vout	Output Pin	
6	GND	Ground Pin	

• DFN1616-6, DFN(PLP)1820-6

Pin No	Symbol	Pin Description	
1	CE	Chip Enable Pin ("H" Active)	
2	Vfb	Feedback Pin	
3	Lx	Switching Pin (Open Drain Output)	
4	GND	Ground Pin	
5	Vdd	Input Pin	
6	Vout	Output Pin	

*) Tab is GND level. (They are connected to the reverse side of this IC.)

The tab is better to be connected to the GND, but leaving it open is also acceptable.

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• SOT-23-6

Pin No	Symbol	Pin Description	
1	CE	Chip Enable Pin ("H" Active)	
2	Vout	Output Pin	
3	Vdd	Input Pin	
4	Lx	Switching Pin (Open Drain Output)	
5	GND	Ground Pin	
6	Vfb	Feedback Pin	

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ABSOLUTE MAXIMUM RATINGS

ADJUL						
Symbol		Item				
Vin	V _{IN} Pin Voltage			-0.3 to 6.5	V	
Vce	CE Pin Voltage			-0.3 to VIN+0.3	V	
Vfb	VFB Pin Voltage			-0.3 to VIN+0.3	V	
Vout	Vout Pin Voltage			-0.3 to 25.0	V	
VLX	Lx Pin Voltage			-0.3 to 25.0	V	
LX	Lx Pin Current	Lx Pin Current			mA	
		Standard Test Land Pattern	WLCSP-6-P1	633		
PD	Power Dissipation*		DFN1616-6	2400	mW	
		JEDEC STD. 51-7 Test Land Pattern	DFN(PLP)1820-6	2200		
			SOT-23-6	660		
Tj	Junction Temperature Range			-40 to 125	°C	
Tstg	Storage Temperature	-55 to 125	°C			

*) For Power Dissipation, please refer to POWER DISSIPATION.

ABSOLUTE MAXIMUM RATINGS

Electronic and mechanical stress momentarily exceeded absolute maximum ratings may cause the permanent damages and may degrade the life time and safety for both device and system using the device in the field. The functional operation at or over these absolute maximum ratings is not assured.

RECOMMENDED OPERATING CONDITIONS

Symbol	Item	Rating	Unit
V _{IN}	Input Voltage	2.3 to 5.5	V
Та	Operating Temperature Range	−40 to 85	°C

RECOMMENDED OPERATING CONDITIONS

All of electronic equipment should be designed that the mounted semiconductor devices operate within the recommended operating conditions. The semiconductor devices cannot operate normally over the recommended operating conditions, even if when they are used over such ratings by momentary electronic noise or surge. And the semiconductor devices may receive serious damage when they continue to operate over the recommended operating conditions.

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ELECTRICAL CHARACTERISTICS

• R1200x

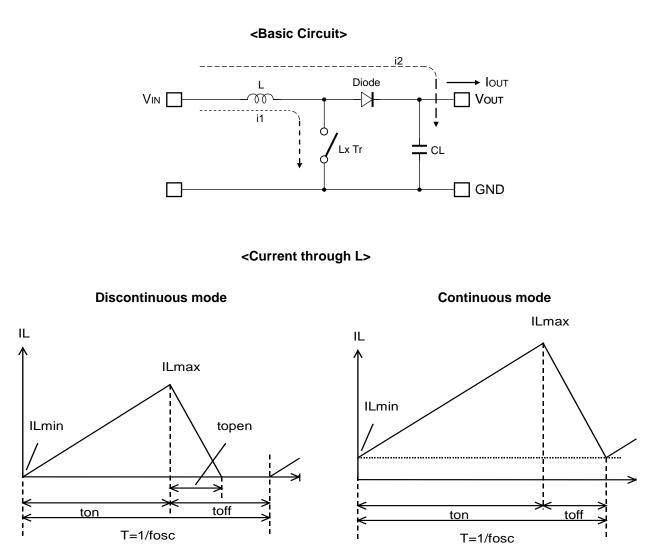
Ta=25°C

Symbol	Item	Condi	tions	Min.	Тур.	Max.	Unit
DD	Supply Current	VIN=5.5V, VFB=0V, Lx at no load			0.5	1.0	mA
Istandby	Standby Current	VIN=5.5V, VCE=0V			0	3.0	μA
VUVLO1	UVLO Detector Threshold	V _{IN} falling		1.9	2.0	2.1	V
Vuvlo2	UVLO Released Voltage	V _{IN} rising			V _{UVLO1} +0.10	2.25	V
Vсен	CE Input Voltage "H"	Vin=5.5V		1.5			V
Vcel	CE Input Voltage "L"	VIN=2.3V				0.5	V
RCE	CE Pull Down Resistance	VIN=3.6V		600	1200	2200	kΩ
Vfb	VFB Voltage Accuracy	VIN=3.6V		0.985	1.0	1.015	V
∆V _{FB} / ∆Та	VFB Voltage Temperature Coefficient	$V_{IN}=3.6V, -40^{\circ}C \le 10^{-1}$	Ta ≤ 85°C		±150		ppm /°C
FB	VFB Input Current	VIN=5.5V, VFB=0V 0	r 5.5V	-0.1		0.1	μΑ
tstart	Soft-start Time	V _{IN} =3.6V			1.5		ms
Ron	Switch ON Resistance	VIN=3.6V, Isw=100m	ıΑ		1.35		Ω
LXleak	Switch Leakage Current				0	3.0	μΑ
LXlim	Switch Current Limit	VIN=3.6V		400	700	1000	mA
Vnpn	NPN VCE Voltage	INPN=100mA			0.8		V
INPNOFF1	NPN Leakage Current 1	Vout=23V				10	μΑ
NPNOFF2	NPN Leakage Current 2	Vout=0V, Vlx=5.5V				3.0	μΑ
fosc	Oscillator Frequency	VIN=3.6V, VOUT=VFB	=0V	1.0	1.2	1.4	MHz
Maxduty	Maximum Duty Cycle	VIN=3.6V, VOUT=VFB	=0V	86	91		%
			R1200x001x	16	17	18	v
Vovp1	OVP Detector Threshold	Vıℕ=3.6V, Vou⊤ rising	R1200x002x	18	19	20	
		veer nonig	R1200x003x	20	21	22	
Vovp2	OVP Released Voltage	VIN=3.6V, VOUT falling			Vovp1 -1.1		V
DISCHG	Vout Discharge Current	VIN=3.6V, VOUT=0.1V R1200xxxxA			0.7		mA
Ivout	OVP Sense Current	Vin=3.6V, Vout=23V			6.0		μA

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OPERATING DESCRIPTIONS

Operation of Step-Up DC/DC Converter and Output Current



There are two operation modes of the step-up PWM control-DC/DC converter. That is the continuous mode and discontinuous mode by the continuousness inductor.

When the transistor turns ON, the voltage of inductor L becomes equal to V_{IN} voltage. The increase value of inductor current (i1) will be

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As the step-up circuit, during the OFF time (when the transistor turns OFF) the voltage is continually supply from the power supply. The decrease value of inductor current (i2) will be

 $\Delta i2 = (V_{OUT} - V_{IN}) \times \text{topen} / L$Formula 2

At the PWM control-method, the inductor current become continuously when topen=toff, the DC/DC converter operate as the continuous mode.

In the continuous mode, the variation of current of i1 and i2 is same at regular condition.

The duty at continuous mode will be

The average of inductor current at tf = toff will be

If the input voltage = output voltage, the lout will be

If the I_{OUT} value is large than above the calculated value (Formula 6), it will become the continuous mode, at this status, the peak current (ILmax) of inductor will be

 $ILmax = Iout \times Vout / Vin + Vin \times ton / (2 \times L).....Formula 7$

 $ILmax = Iout \times Vout / VIN + VIN \times T \times (Vout - VIN) / (2 \times L \times Vout).....Formula 8$

The peak current value is larger than the IOUT value. In case of this, selecting the condition of the input and the output and the external components by considering of ILmax value.

The explanation above is based on the ideal calculation, and the loss caused by Lx switch and the external components are not included.

The actual maximum output current will be between 50% and 80% by the above calculations. Especially, when the IL is large or V_{IN} is low, the loss of V_{IN} is generated with on resistance of the switch. Moreover, it is necessary to consider Vf of the diode (approximately 0.8V) about V_{OUT} .

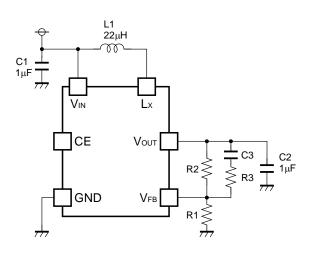
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Shutdown

- At standby mode, the output is completely separated from the input and shutdown by the NPN transistor of internal IC. However, the leakage current is generated when the Lx pin voltage is equal or more than V_{IN} pin voltage at standby mode.
- R1200xxxxA (with auto discharge function): In the term of standby mode, the switch is turned ON between Vout to GND and the Vout capacitor is discharged.
- R1200xxxxB (without auto discharge function): The built-in switch for discharge does not turn on, but the OVP sense resistors between Vout and GND exists as same as A version.
- However, the both version (A/B) has the OVP sense resistance (4 to 5MΩ) between V_{OUT} and GND (refer to OVP sense current (I_{VOUT}) on ELECTRICAL CHARACTERISTICS table) and the current flows through from V_{OUT} to GND.

APPLICATION INFORMATION

• Typical Applications



• Selection of Inductors

The peak current of the inductor at normal mode can be estimated as the next formula when the efficiency is 80%.

ILmax=1.25 x Iout x Vout / VIN + 0.5 x VIN x (Vout - VIN) / (L x Vout x fosc)

In the case of start-up or dimming control by CE pin, inductor transient current flows, and the peak current of it must be equal or less than the current limit of the IC. The peak current should not beyond the rated current of the inductor.

The recommended inductance value is 4.7 μH – 22 $\mu H.$

Table 1 Peak	current	value in	each	condition
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	Condition				
VIN (V)	Vout (V)	lout (mA)	L (μΗ)	ILmax (mA)	
3	14	20	10	215	
3	14	20	22	160	
3	21	20	10	280	
3	21	20	22	225	

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L (μΗ)	Part No.	Rated Current (mA)	Size (mm)
10	LQH32CN100K53	450	3.2 x 2.5 x 1.55
10	LQH2MC100K02	225	2.0 x 1.6 x 0.9
10	VLF3010A-100	490	2.8 x 2.6 x 0.9
10	VLS252010-100	520	2.5 x 2.0 x 1.0
22	LQH32CN220K53	250	3.2 x 2.5 x 1.55
22	LQH2MC220K02	185	2.0 x 1.6 x 0.9
22	VLF3010A-220	330	2.8 x 2.6 x 0.9
4.7	LQH32CN4R7M53	650	3.2 x 2.5 x 1.55

Table 2 Recommended inductors

• Selection of Capacitors

Set $1\mu F$ or more value bypass capacitor C1 between V_{IN} pin and GND pin as close as possible. Set $1\mu F - 4.7\mu F$ or more capacitor C2 between V_{OUT} and GND pin.

		-
	Rated voltage(V)	Part No.
C1	6.3	CM105B105K06
C2	25	GRM21BR11E105K
C3	25	22pF
R1		For Vout Setting
R2		For Vout Setting
R3		2kΩ

Table 3 Recommended components

• External Components Setting

• If the spike noise of V_{OUT} may be large, the spike noise may be picked into V_{FB} pin and make the operation unstable. In this case, use a R3 of the resistance value in the range from $1k\Omega$ to $5k\Omega$ to reduce a noise level of V_{FB}.

• The Method of Output Voltage Setting

• The output voltage can be calculated with divider resistors (R1 and R2) values as the following formula:

Output Voltage = $V_{FB} \times (R1 + R2) / R1$

The total value of R1 and R2 should be equal or less than 300kΩ. Make the V_{IN} and GND line sufficient. The large current flows through the V_{IN} and GND line due to the switching. If this impedance (V_{IN} and GND line) is high, the internal voltage of the IC may shift by the switching current, and the operating may become unstable. Moreover, when the built-in Lx switch is turn OFF, the spike noise caused by the inductor may be generated. As a result of this, recommendation voltage rating of capacitor (C2) value is equal 1.5 times larger or more than the setting output voltage.

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TECHNICAL NOTES

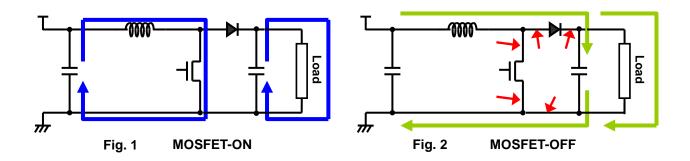
Current Path on PCB

The current paths in an application circuit are shown in Fig. 1 and 2.

A current flows through the paths shown in Fig. 1 at the time of MOSFET-ON, and shown in Fig. 2 at the time of MOSFET-OFF. In the paths pointed with red arrows in Fig. 2, current flows just in MOSFET-ON period or just in MOSFET-OFF period. Parasitic impedance/inductance and the capacitance of these paths influence stability of the system and cause noise outbreak. So please minimize this side effect. In addition, please shorten the wiring of other current paths shown in Fig. 1 and 2 except for the paths of LED load.

• Layout Guide for PCB

- Please shorten the wiring of the input capacitor (C1) between V_{IN} pin and GND pin of IC. The GND pin should be connected to the strong GND plane.
- The area of Lx land pattern should be smaller.
- Please put output capacitor (C2) close to the Vour pin.
- Please make the GND side of output capacitor (C2) close to the GND pin of IC.

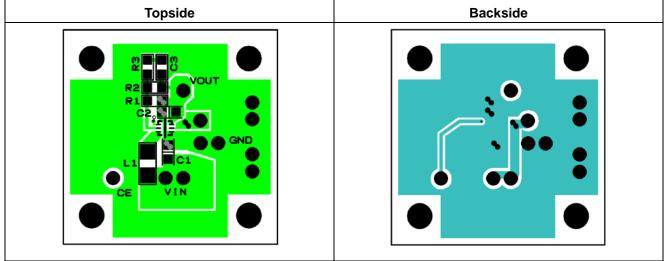


R1200x NO.EA-192-170925

• PCB Layout

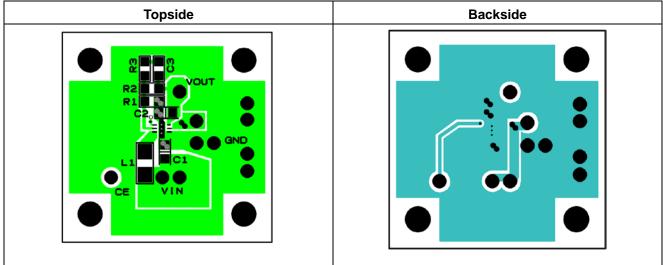
· PKG: DFN1616-6pin

R1200L Typical Board Layout



PKG:DFN(PLP)1820-6pin

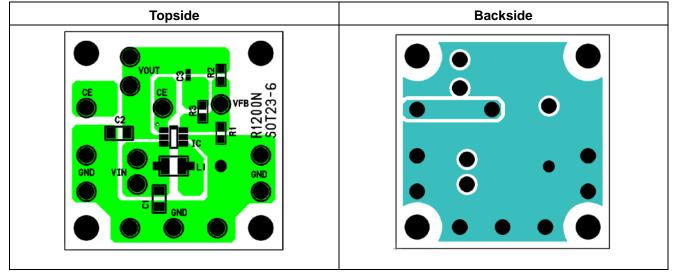
R1200K Typical Board Layout



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PKG:SOT-23-6pin

R1200N Typical Board Layout



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Set Vour=9V

V∾≊2.8V

V≥=3.6V

V≈=4.2V

Vr×≈5.0V

Set Vour=18V

160

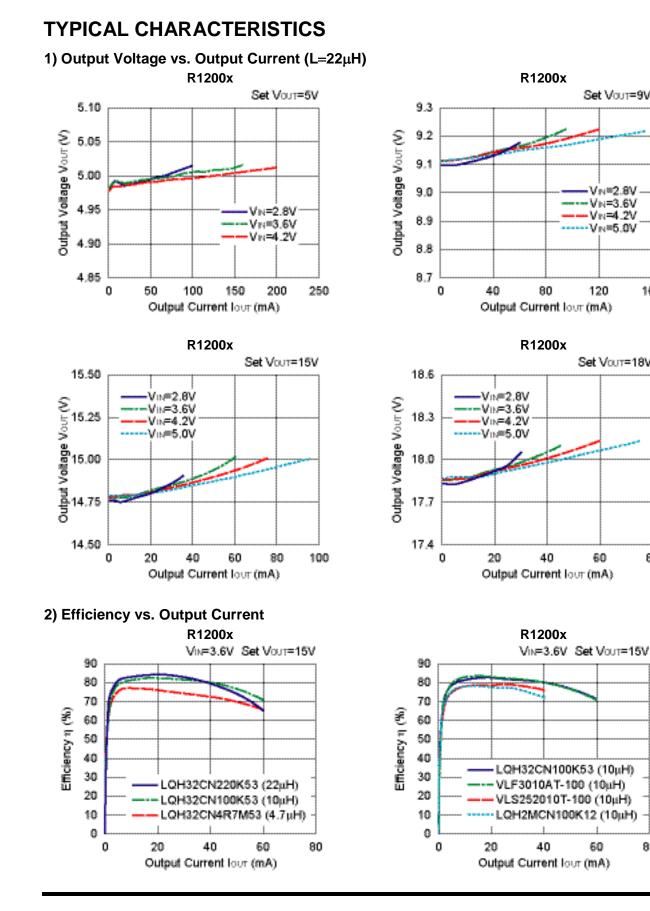
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80

60

60

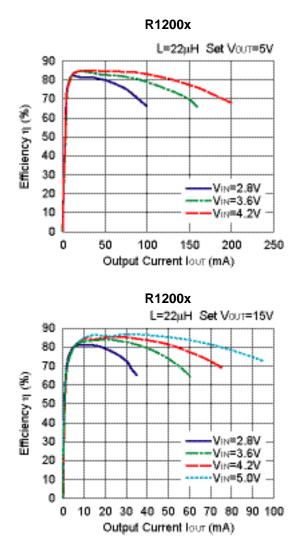
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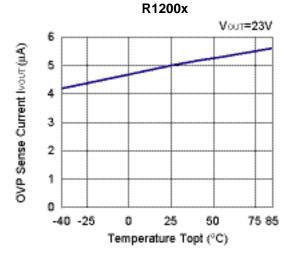


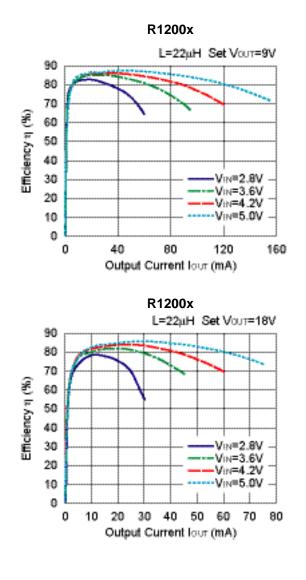


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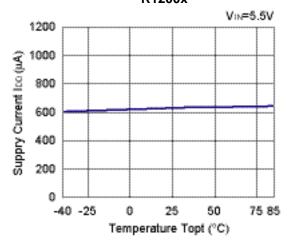


3) OVP Sense Current vs. Temperature



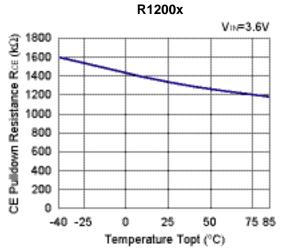


4) Supply Current vs. Temperature R1200x



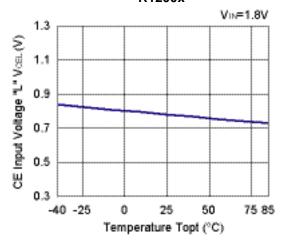
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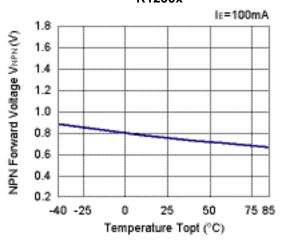


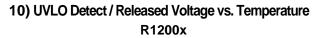
5) CE Pulldown Resistance vs. Temperature

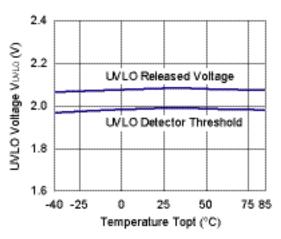
6) CE Input Voltage "L" vs. Temperature R1200x

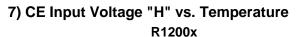


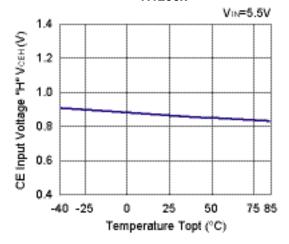


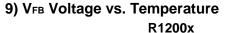


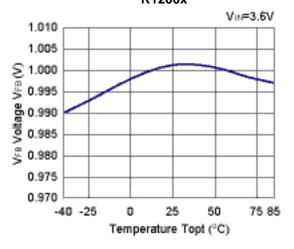






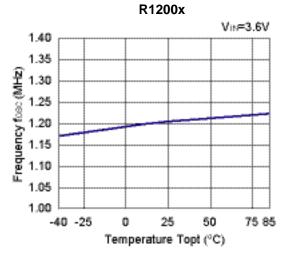


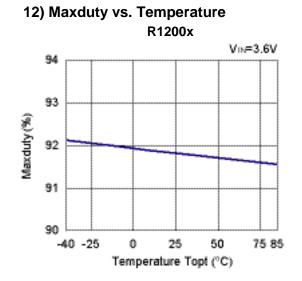




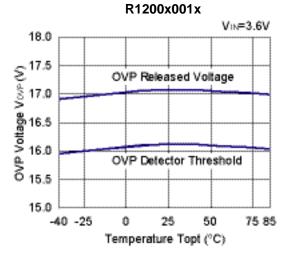
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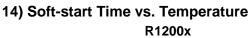


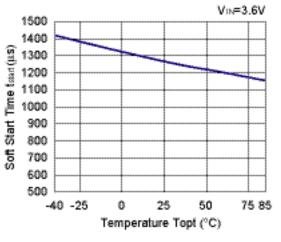


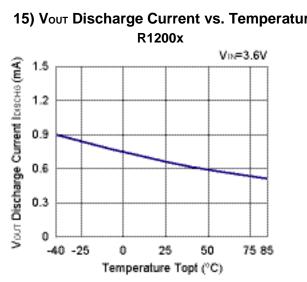








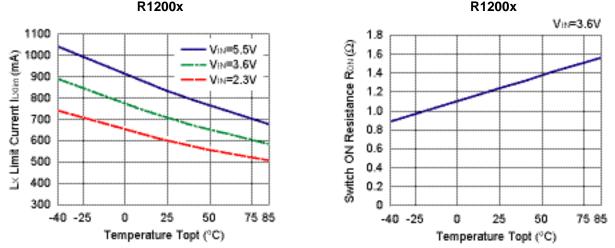




15) VOUT Discharge Current vs. Temperature



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Output Voltage Vour (V)

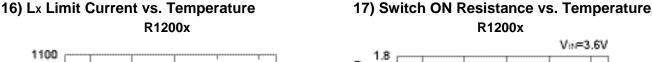
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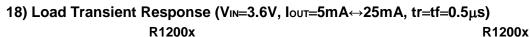
15.0

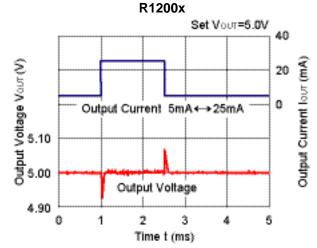
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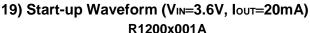
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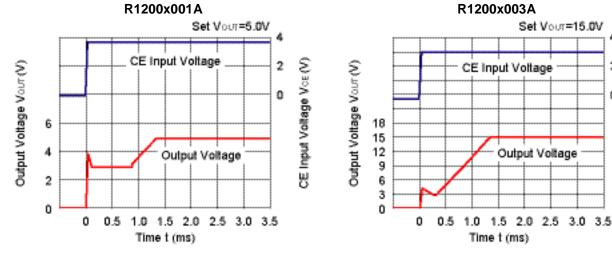
1











Set Vour=15.0V

4

Output Current 5mA ←> 25mA

Output Voltage

Time t (ms)

3

2

40

20

0

5

4

2

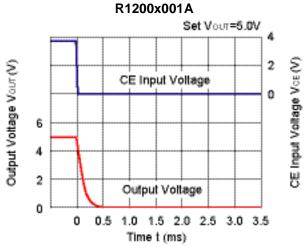
0

CE Input Voltage Vor (V)

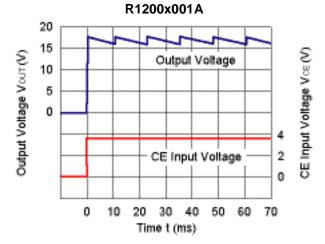
Output Current lour (mA)

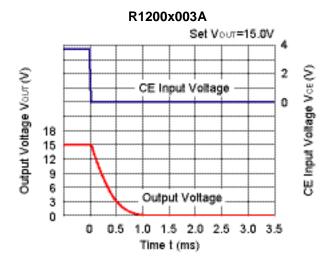
NO.EA-192-170925











POWER DISSIPATION

WLCSP-6-P1

Ver. A

The power dissipation of the package is dependent on PCB material, layout, and environmental conditions. The following conditions are used in this measurement.

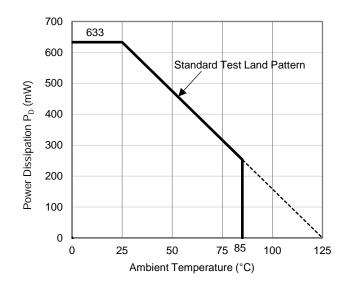
Measurement Conditions

	Standard Test Land Pattern
Environment	Mounting on Board (Wind Velocity = 0 m/s)
Board Material	Glass Cloth Epoxy Plastic (Double-Sided Board)
Board Dimensions	40 mm × 40 mm × 1.6 mm
Copper Ratio	Top Side: Approx. 50%
	Bottom Side: Approx. 50%
Through-holes	-

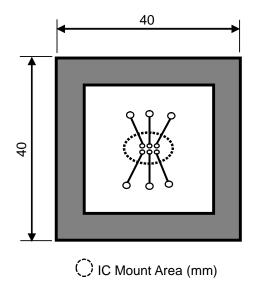
Measurement Result

(Ta = 25°C, Tjmax = 125°C)

	Standard Test Land Pattern	
Power Dissipation	633 mW	
Thermal Resistance	θja = (125 - 25°C) / 0.633 W = 158°C/W	



Power Dissipation vs. Ambient Temperature

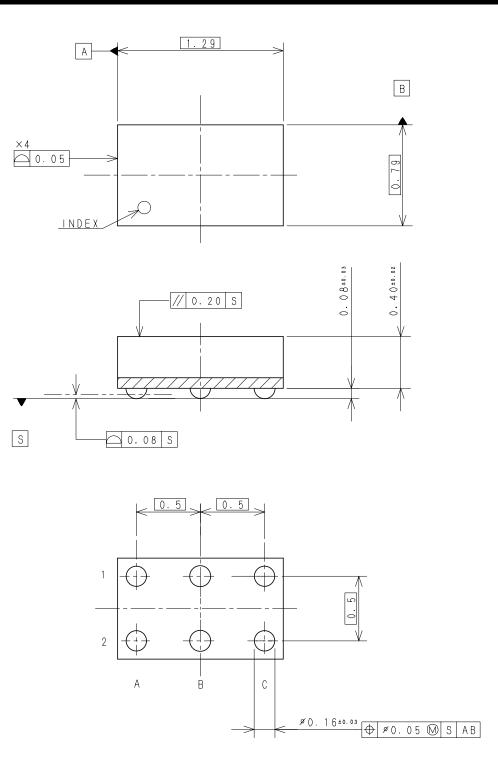


Measurement Board Pattern

PACKAGE DIMENSIONS

WLCSP-6-P1

Ver. A





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POWER DISSIPATION

DFN1616-6

Ver. A

The power dissipation of the package is dependent on PCB material, layout, and environmental conditions. The following conditions are used in this measurement.

Measurement Conditions

Item	Measurement Conditions (JEDEC STD. 51-7)	
Environment	Mounting on Board (Wind Velocity = 0 m/s)	
Board Material	Glass Cloth Epoxy Plastic (Four-Layer Board)	
Board Dimensions	76.2 mm × 114.3 mm × 0.8 mm	
Copper Ratio	1st Layer: Less than 95% of 50 mm Square 2nd, 3rd, 4th Layers: Approx. 100% of 50 mm Square	
Through-holes	φ 0.2 mm × 15 pcs	

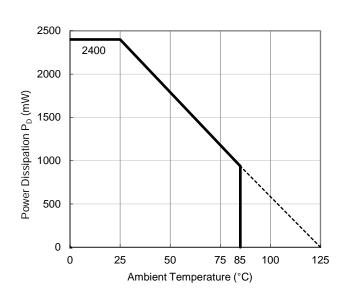
Measurement Result

(Ta = 25°C, Tjmax = 125°C)

Item	Measurement Result
Power Dissipation	2400 mW
Thermal Resistance (θ ja)	θja = 41°C/W
Thermal Characterization Parameter (ψjt)	ψjt = 11°C/W

 $\theta ja:$ Junction-to–ambient thermal resistance.

wit: Junction-to-top of package thermal characterization parameter.



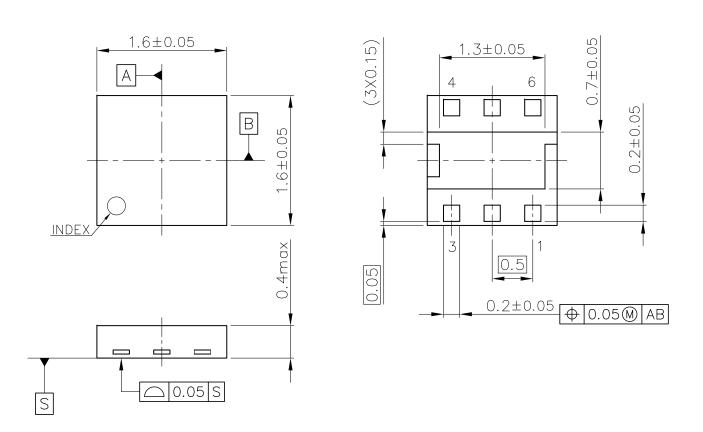
Power Dissipation vs. Ambient Temperature

Measurement Board Pattern

PACKAGE DIMENSIONS

DFN1616-6

Ver. A



DFN1616-6 Package Dimensions (Unit: mm)

^{*} The tab on the bottom of the package shown by blue circle is a substrate potential (GND). It is recommended that this tab be connected to the ground plane on the board but it is possible to leave the tab floating.



POWER DISSIPATION

DFN(PLP)1820-6

Ver. A

The power dissipation of the package is dependent on PCB material, layout, and environmental conditions. The following conditions are used in this measurement.

Measurement Conditions

Item	Measurement Conditions (JEDEC STD. 51-7)	
Environment	Mounting on Board (Wind Velocity = 0 m/s)	
Board Material	Glass Cloth Epoxy Plastic (Four-Layer Board)	
Board Dimensions	76.2 mm × 114.3 mm × 0.8 mm	
Copper Ratio	1st Layer: Less than 95% of 50 mm Square 2nd, 3rd, 4th Layers: Approx. 100% of 50 mm Square	
Through-holes	φ 0.2 mm × 34 pcs	

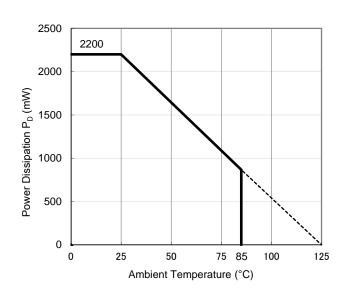
Measurement Result

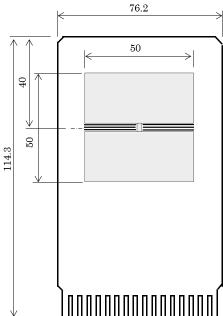
(Ta = 25°C, Tjmax = 125°C)

Item	Measurement Result
Power Dissipation	2200 mW
Thermal Resistance (θ ja)	θja = 45°C/W
Thermal Characterization Parameter (wjt)	ψjt = 18°C/W

 θ ja: Junction-to-ambient thermal resistance.

wit: Junction-to-top of package thermal characterization parameter.





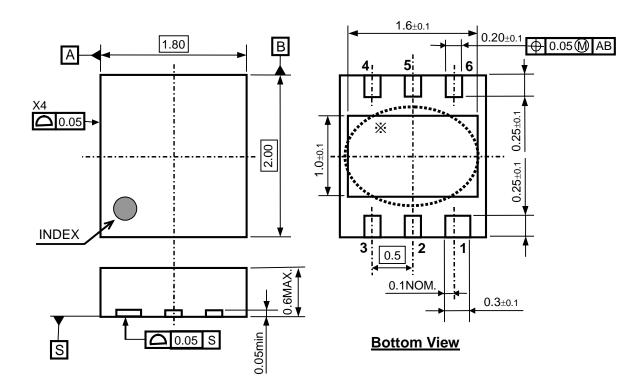
Power Dissipation vs. Ambient Temperature

Measurement Board Pattern

PACKAGE DIMENSIONS

DFN(PLP)1820-6

Ver. A



DFN(PLP)1820-6 Package Dimensions (Unit: mm)

^{*} The tab on the bottom of the package is substrate level (GND). It is recommended that the tab be connected to the ground plane on the board, or otherwise be left floating.



POWER DISSIPATION

SOT-23-6

Ver. A

The power dissipation of the package is dependent on PCB material, layout, and environmental conditions. The following conditions are used in this measurement.

Measurement Conditions

Item	Measurement Conditions (JEDEC STD. 51-7)	
Environment	Mounting on Board (Wind Velocity = 0 m/s)	
Board Material	Glass Cloth Epoxy Plastic (Four-Layer Board)	
Board Dimensions	76.2 mm × 114.3 mm × 0.8 mm	
Copper Ratio	1st Layer : Less than 95% of 50 mm Square 2nd, 3rd, 4th Layers: Approx. 100% of 50 mm Square	
Through-holes	φ 0.3 mm × 7 pcs	

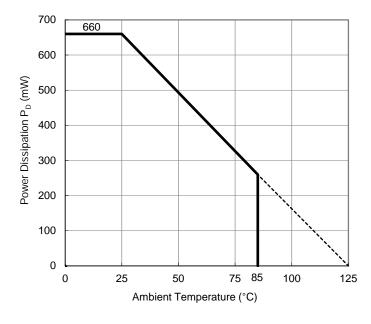
Measurement Result

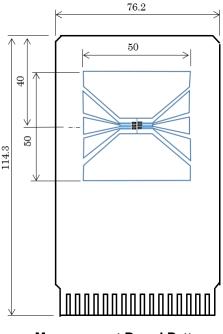
(Ta = 25°C, Tjmax = 125°C)

Item	Measurement Result
Power Dissipation	660 mW
Thermal Resistance (θja)	θja = 150°C/W
Thermal Characterization Parameter (ψjt)	ψjt = 51°C/W

 θ ja: Junction-to-ambient thermal resistance.

wit: Junction-to-top of package thermal characterization parameter





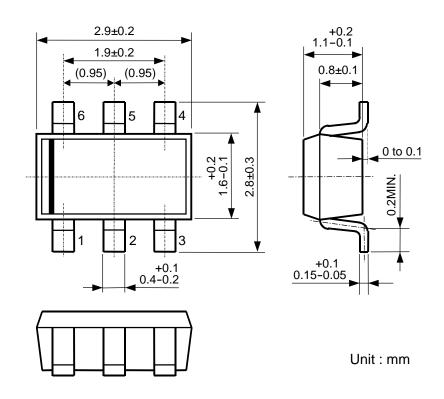
Power Dissipation vs. Ambient Temperature

Measurement Board Pattern

PACKAGE DIMENSIONS

SOT-23-6

Ver. A





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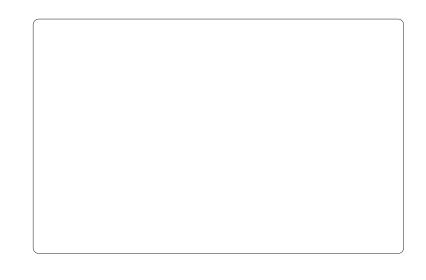
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